

Preliminary

# **SPECIFICATION**

## **Chip Antenna**

**Model No. : SENA\_029**

<b>WRITTEN</b>	<b>CHECKED</b>	<b>APPROVED</b>

**December 31, 2009**

**Notes**

**The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.**

# 1. SPECIFICATIONS

## 1.1. Electrical Specifications

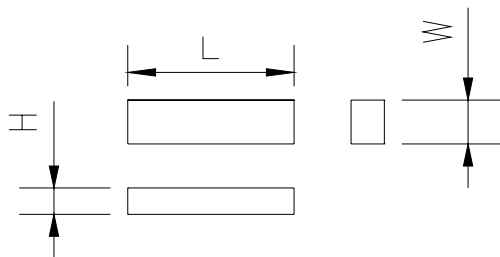
ITEM	SPEC.	Unit
Frequency	2400-2485	MHz
Bandwidth @ VSWR 2.5:1	100	MHz
Max. Gain	0.5	dBi
Polarization	Linear	
Azimuth Beam Pattern	Omni-directional	
Impedance	50	$\Omega$

※ These values are measured on the matched reference test board.

## 1.2. Mechanical Specifications

Electrode	Silver	
Dimensions (L x W x H)	5.2 x 2.0 x 1.2	mm
Operating Temperature	-40 ~ +85	°C

## 1.3. Appearance and Dimensions



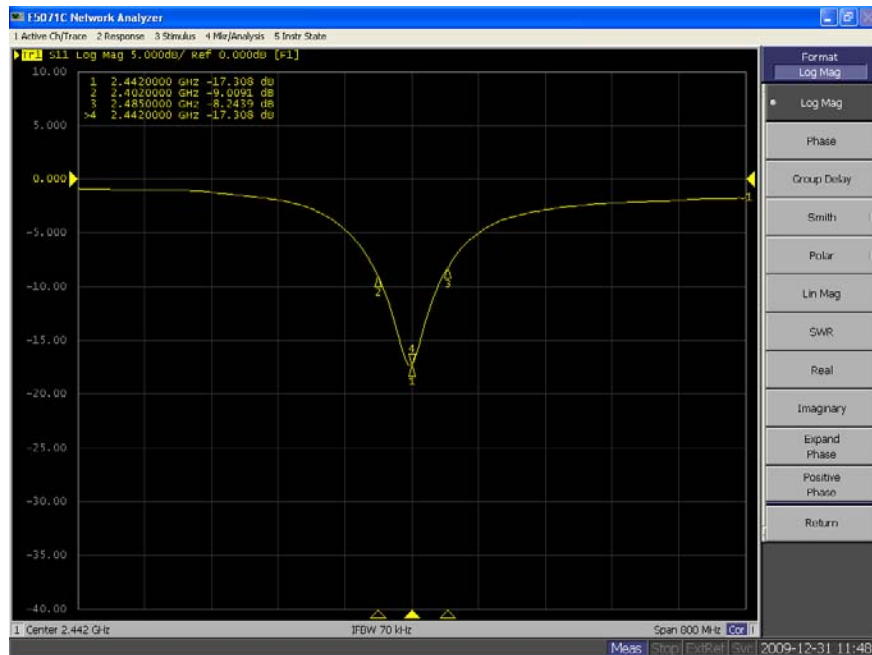
- unit : mm  
- Tolerance :  $\pm 0.15$

L	5.2
W	2.0
H	1.2

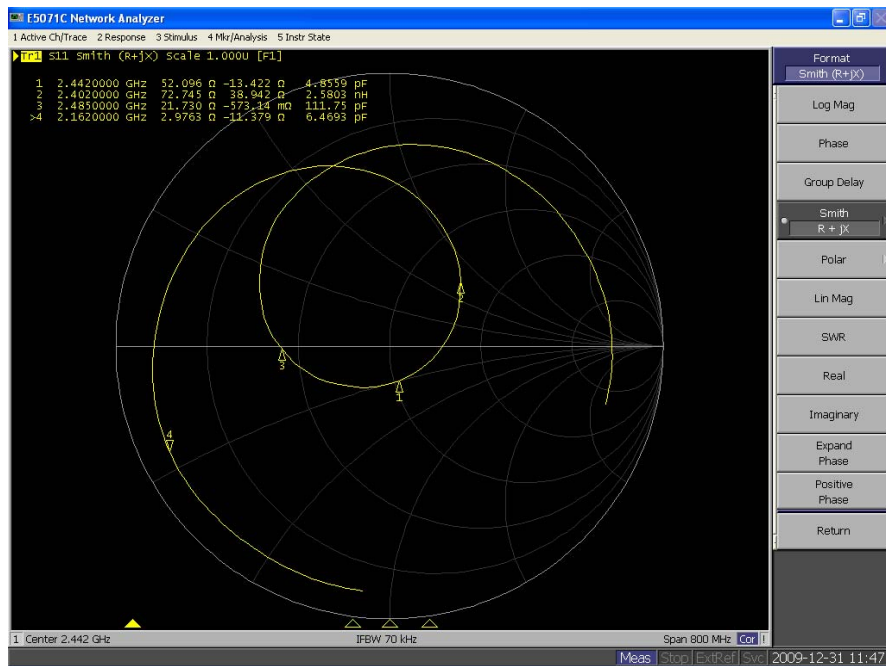
## 2. MEASUREMENT

### 2.1. Electrical Characteristic

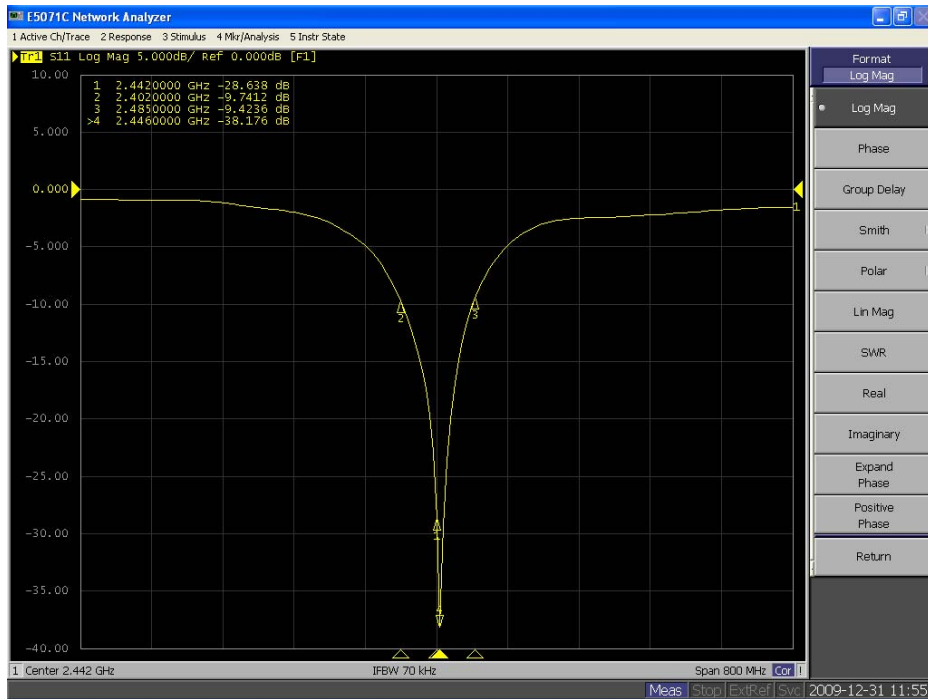
#### A. $S_{11}$ (Return Loss) - (No.29) <= without Jig Board



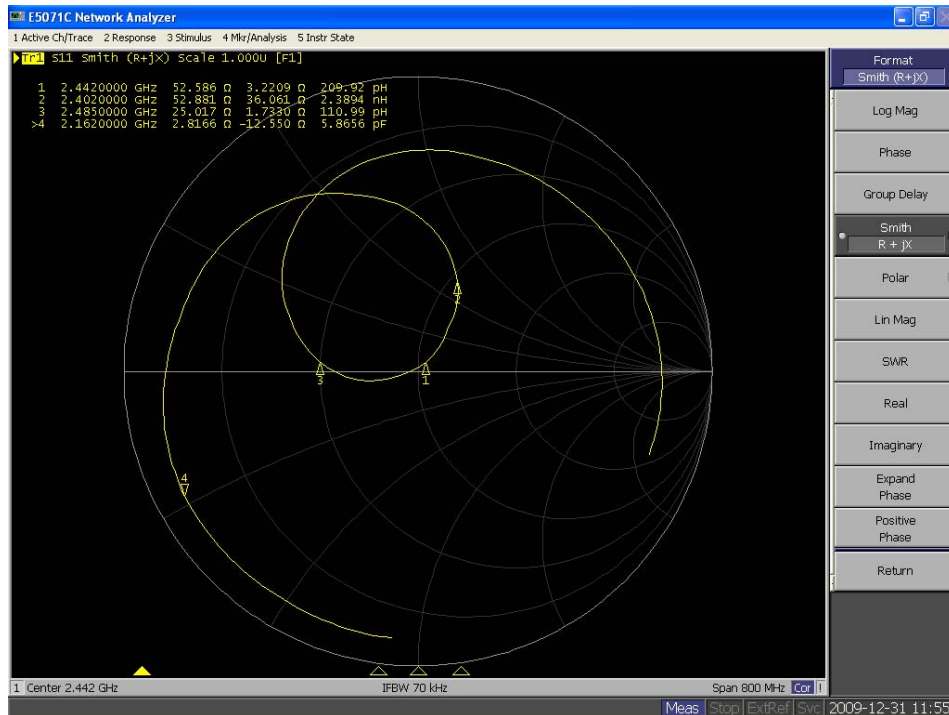
#### B. $S_{11}$ (Smith chart) - (No.29) <= without Jig Board



## A. $S_{11}$ (Return Loss) - (No.29) <= with Jig Board

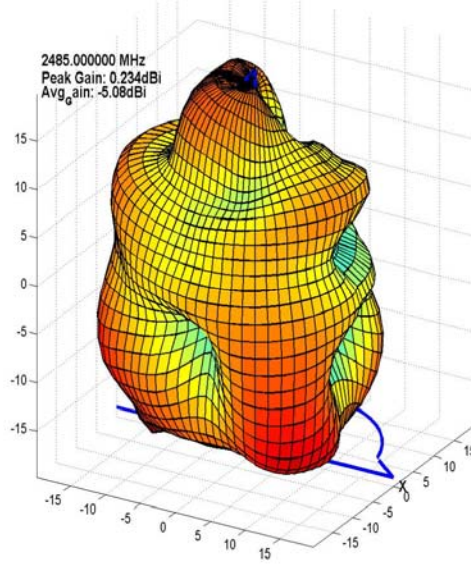
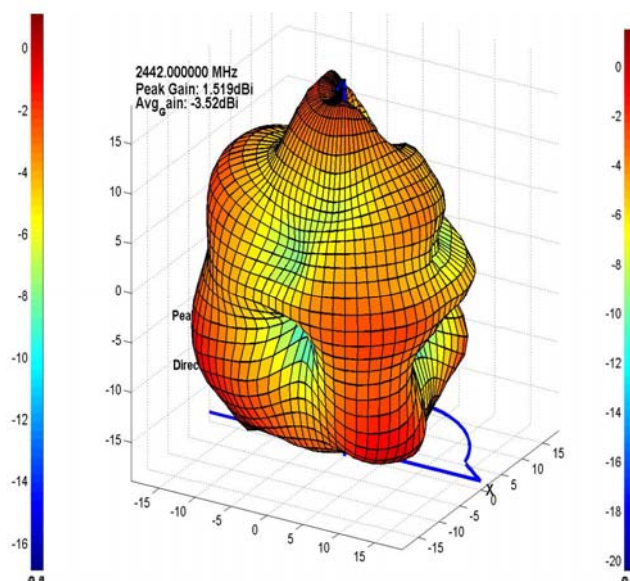
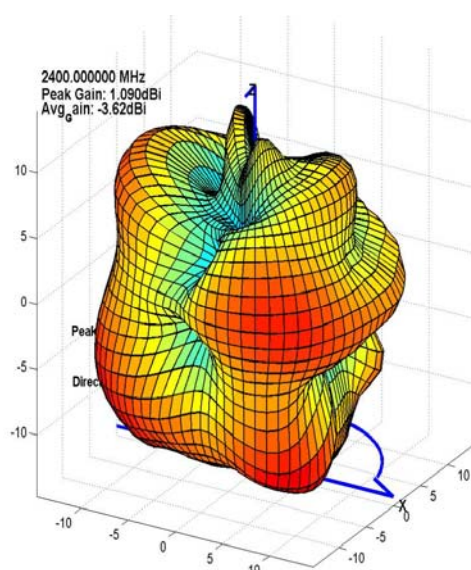


## B. $S_{11}$ (Smith chart) - (No.29) <= with Jig Board

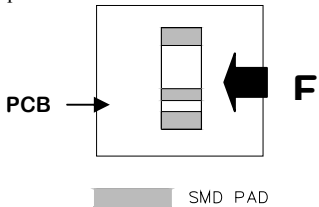


### 3. Radiation Data

Frequency	Efficiency	Average Gain			Max Gain			Max Position	Directivity
		Ver	Hor	Total	Ver	Hor	Total		
2400 MHz	43.4 %	-9.4 dBi	-5.0 dBi	-3.6 dBi	-0.6 dBi	0.5 dBi	0.1 dBi	Theta120/Pie165	4.71 dB
2442 MHz	44.4 %	-9.0 dBi	-5.0 dBi	-3.5 dBi	-0.3 dBi	0.4 dBi	0.5 dBi	Theta120/Pie165	5.05 dB
2485 MHz	31.0 %	-9.8 dBi	-6.9 dBi	-5.1 dBi	-1.3 dBi	-0.2 dBi	0.2 dBi	Theta120/Pie150	5.32 dB



## 4. RELIABILITY TEST

No	Item	Test condition	Test Requirements
1	Adhesion strength	<p>Applied force on SMD chip till detached point from PCB</p>  <p>PCB →</p> <p>← F</p> <p>■ SMD PAD</p>	<ol style="list-style-type: none"> <li>No mechanical damage by forces applied on the right</li> <li>Strength (F) &gt; 5 kgf</li> </ol>
2	Thermal Shock (Temperature Cycle)	<ol style="list-style-type: none"> <li>1 cycle / step 1 : <math>-40 \pm 3^\circ\text{C}</math>, 30 min step 2 : <math>+85 \pm 3^\circ\text{C}</math>, 30 min</li> <li>Number of cycle : 10</li> <li>Measure after left for 48 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>No visual damage</li> <li>VSWR satisfy</li> </ol>
3	High Temperature Resistance	<ol style="list-style-type: none"> <li>Temperature : <math>+85 \pm 5^\circ\text{C}</math></li> <li>Time : 96 hrs</li> <li>Measure VSWR<sub>C</sub> after left for 24 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>No visual damage</li> <li>VSWR satisfy</li> </ol>
4	Low Temperature Resistance	<ol style="list-style-type: none"> <li>Temperature : <math>-40 \pm 5^\circ\text{C}</math></li> <li>Time : 96 hrs</li> <li>Measure VSWR<sub>C</sub> after left for 48 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>No visual damage</li> <li>VSWR satisfy</li> </ol>
5	Humidity (Steady Condition)	<ol style="list-style-type: none"> <li>Humidity : 85 % RH</li> <li>Temperature : <math>+85 \pm 3^\circ\text{C}</math></li> <li>Time : 96 hrs</li> <li>Measure VSWR<sub>C</sub> after left for 48 hrs min. at room temperature</li> </ol>	<ol style="list-style-type: none"> <li>No visual damage</li> <li>VSWR satisfy</li> </ol>
6	ESD	<ol style="list-style-type: none"> <li>ESD Level : 8KV</li> <li>Mode : Contact discharge</li> <li>Number of cycle : 100</li> </ol> <p>※ Used Ref test PCB.</p>	<ol style="list-style-type: none"> <li>No visual damage</li> <li>VSWR satisfy</li> </ol>

## 4. SOLDERING RECOMMENDATIONS

### 4.1. Reflow Soldering Profile

